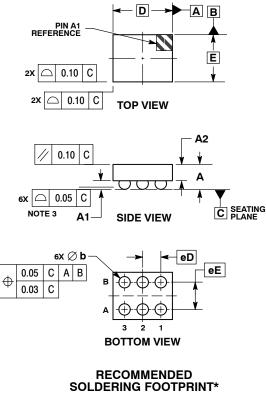
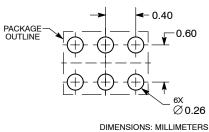


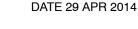


SCALE 4:1





*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



NOTES: 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

 CONTROLLING DIMENSION: MILLIMETERS.
COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

CROWNS OF SOLDER				
	MILLIMETERS			
DIM	MIN	MAX		
Α	0.50	0.62		
A1	0.17	0.23		
A2	0.33	0.39		
b	0.24	0.29		
D	1.31 BSC			
E	1.04 BSC			
eD	0.40 BSC			
еE	0.60 BSC			

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code

- A = Assembly Location
- Y = Year
- WW = Work Week
- = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " •", may or may not be present.

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